Final Product Change Notification	201810025F01

Issue Date: 18-Nov-2018
Effective Date: 16-Feb-2019

Management Summary

Completion of MST Final Test Platform expansion / relocation from the NXP ATTJ Tianjin, China test site to the KESM Industries Tianjin, China test site for supply assurance.

Change Category

☐ Wafer Fab Process	☐ Assembly Process	☐ Product Marking	☑ Test Location	☐ Design
☐ Wafer Fab Materials	☐ Assembly Materials	☐ Mechanical Specification	☐ Test Process	☐ Errata
☐ Wafer Fab Location	☐ Assembly Location	☐ Packing/Shipping/Labeling	☐ Test Equipment	☐ Electrical spec./Test coverage
☐ Firmware	☐ Other			

MST Final Test Platform Expansion / Relocation from ATTJ to KESM - Completion

Description of Change

Previously NXP Semiconductors announced with PCN 201704014F01 from April 2017, the first phase of the MST Final Test platform expansion / relocation from the NXP ATTJ Tianjin, China test site to the KESM Industries Tianjin, China test site. Additional floor space was required at the ATTJ site for newer / more complex test platforms and resulted in the relocation of the legacy MST test platform and associated hardware to KESM.

NXP Semiconductors now announces with this PCN 201810025F01 the completion of this expansion / relocation for the remaining products. So, this is a completion of the previously announced test site expansion, for the remaining products that were not included in the first phase. Most customers already have approved the first phase activity, as announced in PCN 201704014F01.

Please see the attached qualification results and change summary for additional details.

Reason for Change

Qualification of KESM Industries Tianjin, China is required for customer supply assurance.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Not applicable

Production

Planned first shipment 16-Feb-2019

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Disposition of Old Products

Existing inventory will be shipped until depleted

Related Notifications

Notification	Issue Date	Effective Date	Title
201704014F01	30-Apr-2017	14-Jun-2017	MST Final Test Platform Expansion / Relocation from ATTJ to KESM

Additional information

Self qualification: view online
Additional documents: view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 18-Dec-2018.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist direct

Name Kees van Hasselt
Position Quality Account Manager
e-mail address mailto:ivn.customer.service@nxp.com?subject=Support

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Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

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NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands